

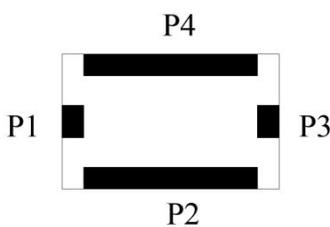
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

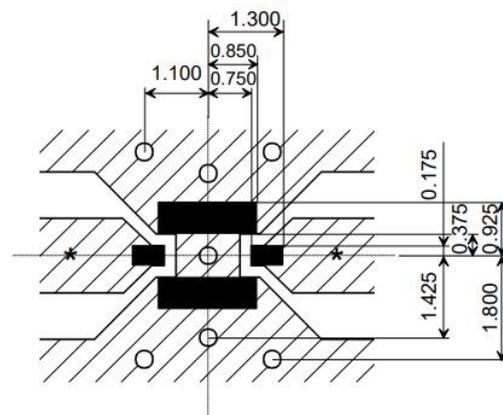
NO.	Parameter	SPC
1	Frequency range	6240-8240 MHz
2	Insertion Loss	2.0dB max. at +25°C 2.3dB max. at -40~+85°C
3	Attenuation	30 dB min. @ 698-2200 MHz 30 dB min. @ 2300-3800 MHz 19 dB min. @ 5150-5470 MHz 3 dB min. @ 5470-5725 MHz 17 dB min. @ 12500-16500 MHz 6 dB min. @ 18700-20000 MHz
4	VSWR (In BW)	2.21 max.
5	Port Impedance	50Ω
6	Power	0.5W max.
7	Operation Temperature Range	-40°C ~ +85°C

Construction



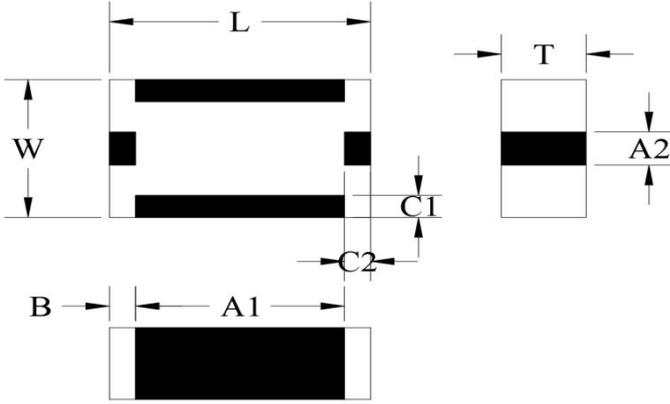
PIN	Connection
1	Input port
2	GND
3	Output port
4	GND

Mounting Considerations

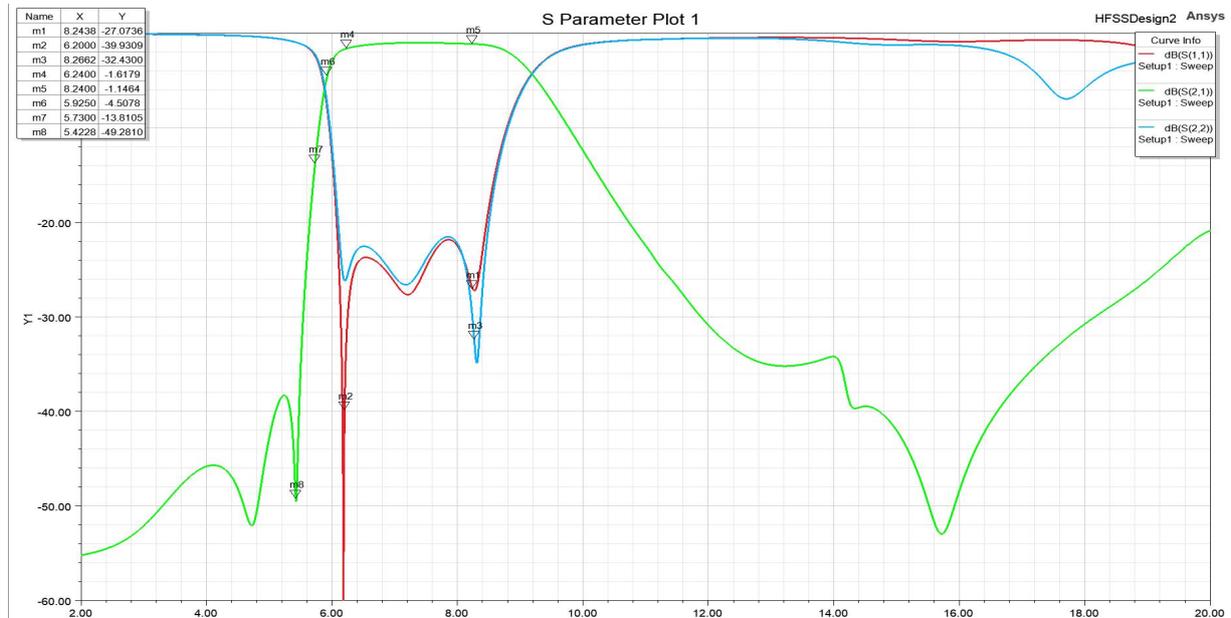


Unit: mm
Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

Dimensions

Figure	Symbol	Dimension (mm)
	L	2.0 ± 0.10
	W	1.25 ± 0.10
	T	0.7MAX
	A1	1.5 ± 0.10
	A2	0.3 ± 0.10
	B	0.25 ± 0.10
	C1	0.2 ± 0.10
	C2	0.2 ± 0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.